

ABSTRACT

It is to provide a curable resin composition which is curable at room temperature, has fluidity, is excellent in workability and provides a cured product
5 having high thermal conductivity and being excellent in flexibility.

A curable resin composition comprising a (meth)acrylate monomer, an organic peroxide, a decomposition accelerator for the organic peroxide, and
10 an inorganic filler, wherein the inorganic filler has a particle size distribution such that it has peak diameters at least in the respective regions of from 3 to 10 μm and from 30 to 70 μm , and the mode diameter is from 30 to 70 μm and the median diameter is from 5 to 40 μm .